08827 0592560

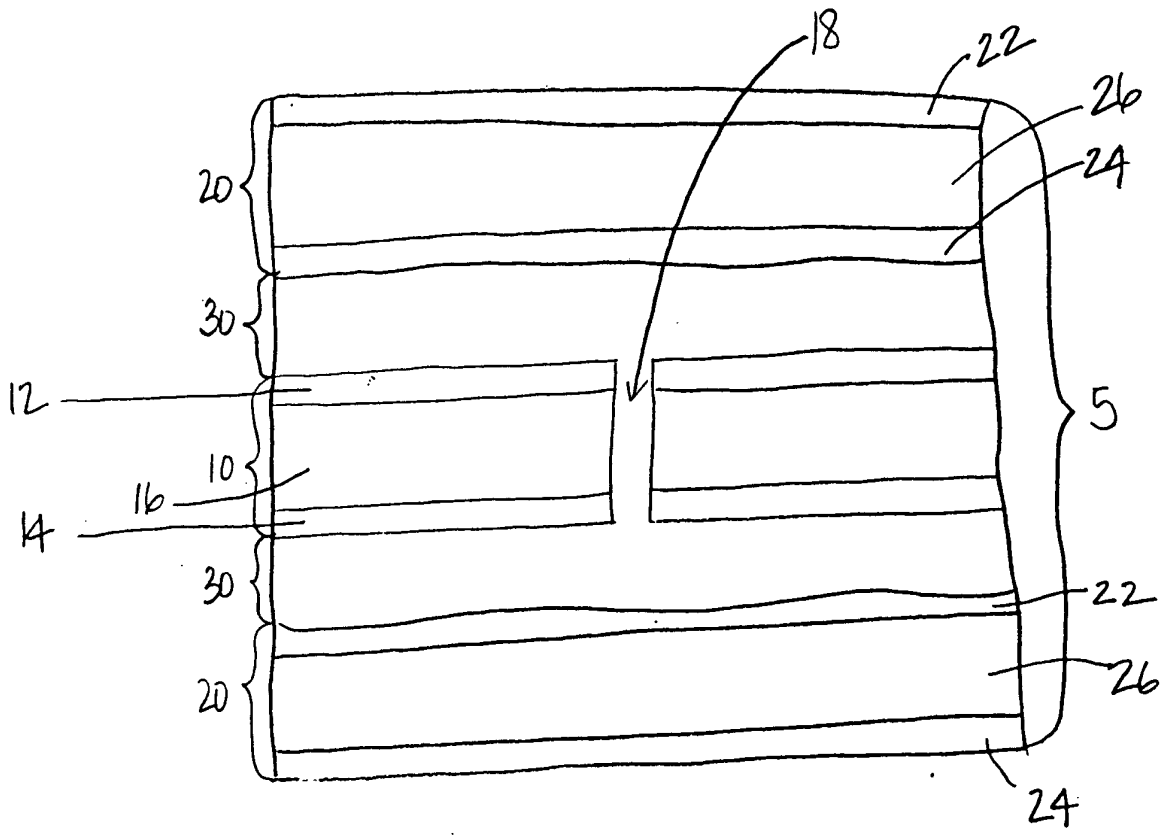


Figure 1

00827 85925260

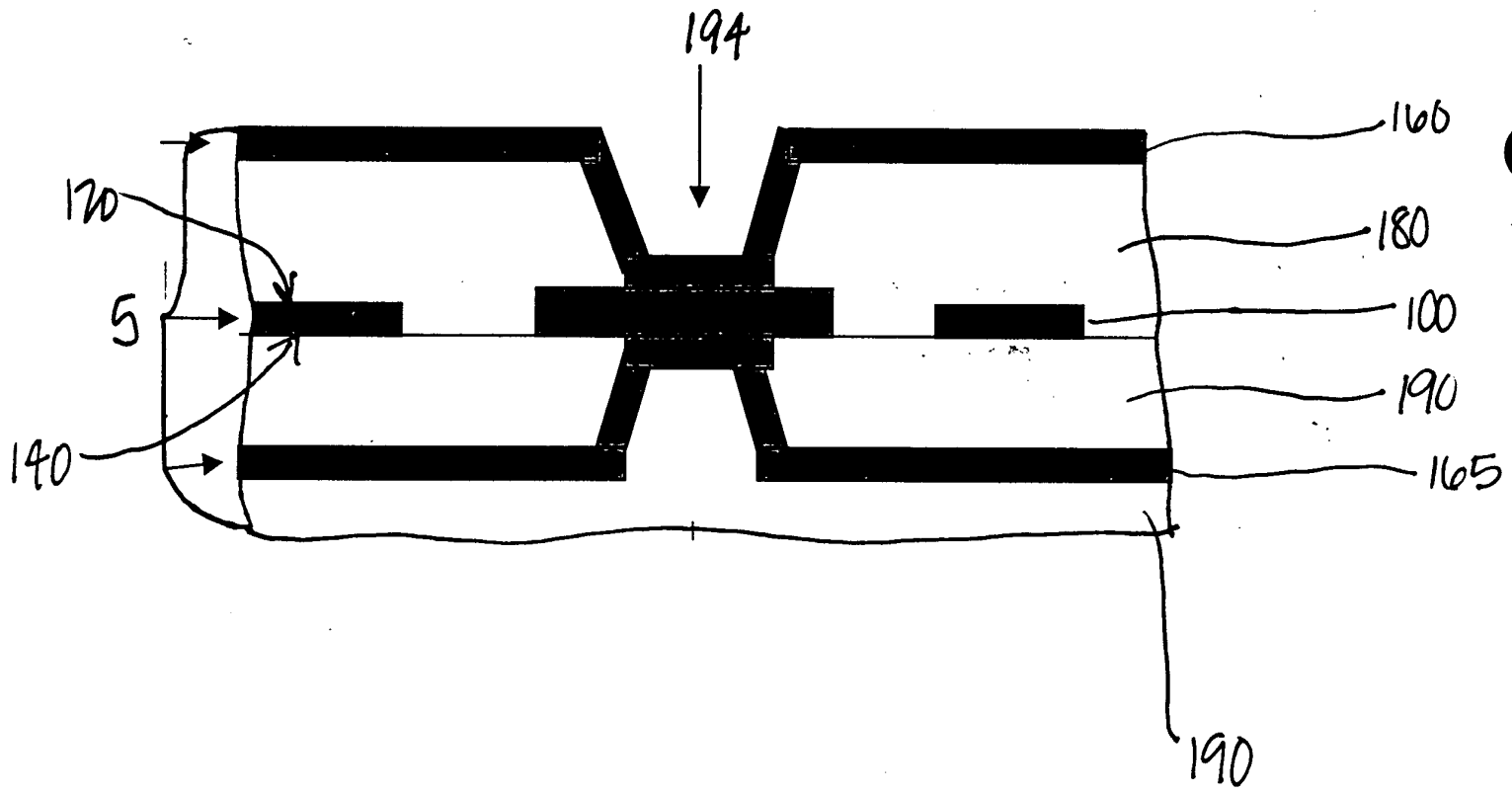


Figure 2

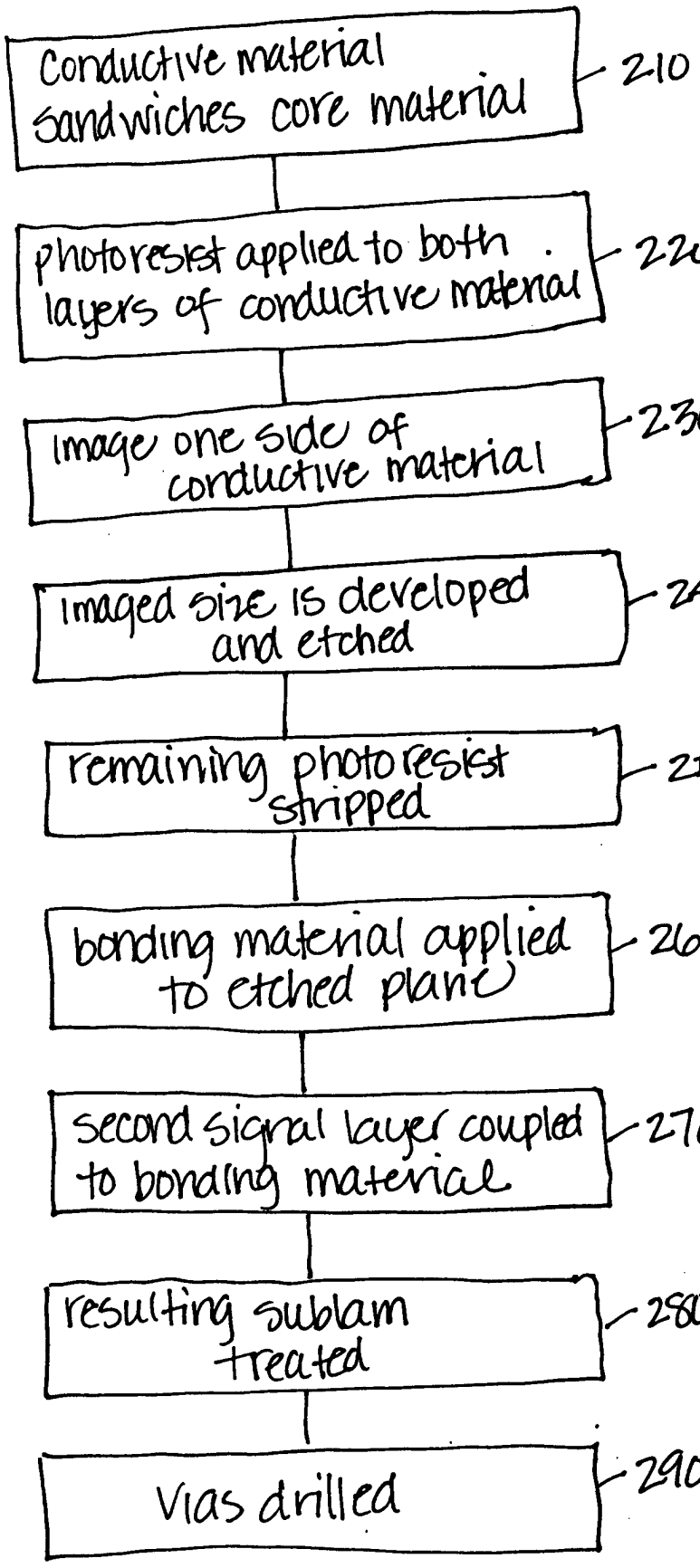
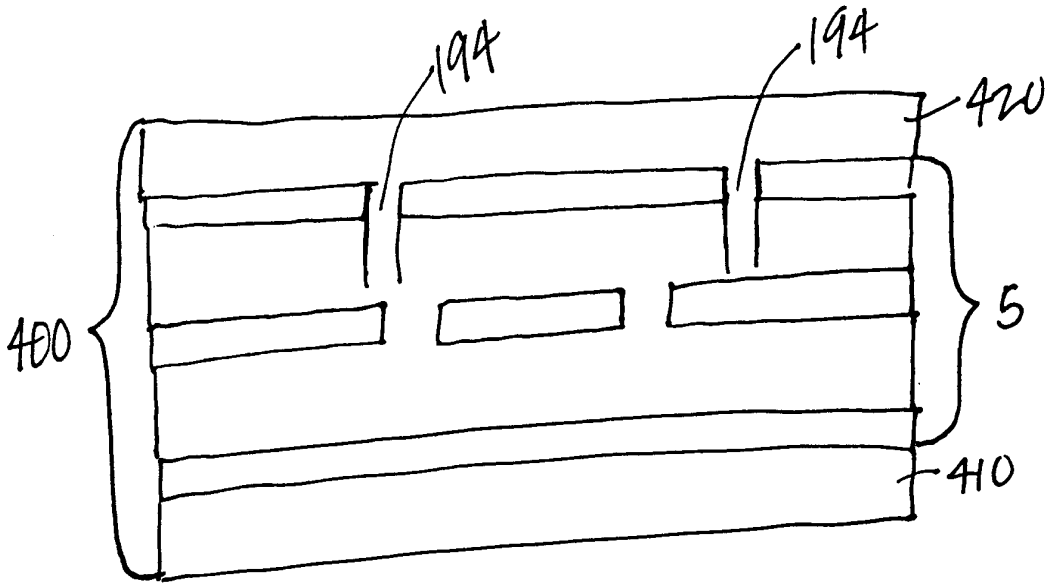

Conductive material sandwiches core material
210
photoresist applied to both layers of conductive material
220
Image one side of conductive material
230
Imaged size is developed and etched
240
remaining photoresist stripped
250
bonding material applied to etched plane
260
second signal layer coupled to bonding material
270
resulting sublam treated
280
Vias drilled
290

Figure 3

006227 "2592760



Group 4